

How Semiconductors are enabling Electric Vehicle revolution



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Infineon at a glance

Business Segments Revenue*



Financials



Employees







For further information: Infineon Annual Report 2020





Three essential ingredients for enabling the EV revolution







Application Scope

Main Inverter enables the bi-directional power conversion between HV battery and e-motor:

- > DC from HV battery → AC for e-motor
- > Regenerative braking \rightarrow power back to battery
- > Enable vehicle motion upon torque request





Infineon offers key components for inverters \rightarrow System cost focus





2020 average xEV semiconductor content by degree of electrification



* Non-Powertrain: average semiconductor content in body, chassis, safety and infotainment application segments

** "power" includes voltage regulators and ASIC; "others" include opto, small signal discretes, memory

Sources: Infineon; based on or includes content supplied by IHS Markit, Automotive Group: Alternative Propulsion Forecast. July 2020; Strategy Analytics: Automotive Semiconductor Demand Forecast 2018-2027 and Automotive Sensor Demand 2018-2027. July 2020

All power technologies are available in-house



Comparison of technologies



Si

- Si remains the mainstream technology
- > Targeting 25 V 6.5 kV
- > Suitable from low to high power

SiC

- SiC complements Si in many applications and enables new solutions
- Targeting 650 V 3.3 kV
- > High power high switching frequency

GaN

- GaN enables new horizons in power supply applications and audio fidelity
- Targeting 80 V 650 V
- Medium power highest switching frequency



System cost reduction \rightarrow Infineon SiC Trench technology

SiC Planar



- ✓ Low complexity process
- ✓ Good shielding of oxide possible

SiC Trench



- ✓ Low channel resistance
- ✓ Shrink potential higher than in planar DMOS

Infineon Trench



- ✓ Low channel resistance
- ✓ Shrink potential higher than in planar DMOS
- ✓ Oxide corners shielded by folded double trench
- ✓ Long experience in trench know-how

 Sophisticated process knowhow needed

- x Very low channel mobility
- x Limited shrink options

x Protection of oxide corners needed

System cost reduction \rightarrow Reduce chip size by superior technology





System cost reduction → More chips/Boule by manufacturing technology





> Field Experience: > 20 BEV platforms in production

- > 17 out of 25 top selling EVs use Infineon Power device
- Shipped 18M power modules/packages → no field failures



- > Migration from Si to SiC is convenient
- > 400V or 800V Bus voltage





Supply security \rightarrow Full control of supply chain



- > Global multi-sourcing strategy for SiC Wafers in place
- > Major investment in In-house Frontend & Backend manufacturing
- > Dual front and back-end site provide robust supply
- > 40+ years experience in manufacturing power devices







Infineon's dependable electronics enables the EV revolution

